# ROHM EMD6 / UMD6N / IMD6A

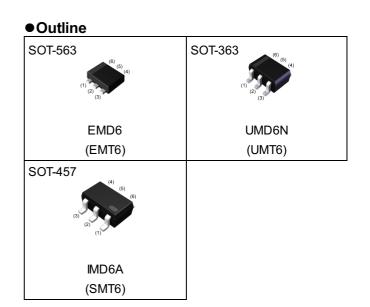
General purpose (dual digital transistor)

<for< th=""><th>DTr1</th><th>(NP</th><th>N)&gt;</th></for<>	DTr1	(NP	N)>

Parameter	Value
V <sub>CEO</sub>	50V
Ι <sub>C</sub>	100mA
R <sub>1</sub>	4.7kΩ

### <For DTr2(PNP)>

Parameter	Value
V <sub>CEO</sub>	-50V
Ι <sub>C</sub>	-100mA
R <sub>1</sub>	4.7kΩ



## Features

- 1)Both the DTA143T chip and DTC143T chip in an EMT or UMT or SMTpackage.
- 2)Mounting possible with EMT3 or UMT3 or SMT3 automatic mounting machines.
- 3)Transistor elements are independent, eliminating interference.
- 4)Mounting cost and area can be cut in half.

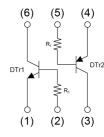
## Application

INVERTER, INTERFACE, DRIVER

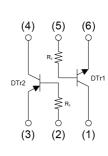
## Packaging specifications

## Inner circuit









Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	Marking
EMD6	SOT-563 (EMT6)	1616	T2R	180	8	8000	D6
UMD6N	SOT-363 (UMT6)	2021	TR	180	8	3000	D6
IMD6A	SOT-457 (SMT6)	2928	T108	180	8	3000	D6

## EMD6 / UMD6N / IMD6A

## ● Absolute maximum ratings (T<sub>a</sub> = 25°C)

Parameter			DTr1(NPN)	DTr2(PNP)	Unit	
Collector-base voltage			50	-50	V	
Collector-emitter voltage			50	-50	V	
Emitter-base voltage			5	-5	V	
Collector current			100	-100	mA	
EMD6/ UMD6N		P <sub>D</sub> <sup>*1*2</sup>	150			
Power dissipation IMD6A			300		-mW/Total	
Junction temperature			150		°C	
Range of storage temperature			-55 to	-55 to +150		

## •Electrical characteristics (T<sub>a</sub> = 25°C) <For DTr1(NPN)>

Deremeter	Cumph of	Conditions	Values			Unit
Parameter Symb		mbol Conditions		Тур.	Max.	Unit
Collector-base breakdown voltage	$BV_{CBO}$	Ι <sub>C</sub> = 50μΑ	50	-	-	V
Collector-emitter breakdown voltage	$BV_{CEO}$	I <sub>C</sub> = 1mA	50	-	-	V
Emitter-base breakdown voltage	$BV_{EBO}$	Ι <sub>Ε</sub> = 50μΑ	5	-	-	V
Collector cut-off current	I <sub>CBO</sub>	V <sub>CB</sub> = 50V	-	-	500	nA
Emitter cut-off current	I <sub>EBO</sub>	$V_{EB} = 4V$	-	-	500	nA
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> = 5mA, I <sub>B</sub> = 0.25mA	-	-	300	mV
DC current gain	h <sub>FE</sub>	V <sub>CE</sub> = 5V, I <sub>C</sub> = 1mA	100	250	600	-
Input resistance	R <sub>1</sub>	-	3.29	4.7	6.11	kΩ
Transition frequency	$f_{T}^{*4}$	V <sub>CE</sub> = 10V, I <sub>E</sub> = -5mA, f = 100MHz	-	250	-	MHz

## •Electrical characteristics (T<sub>a</sub> = 25°C) <For DTr2(PNP)>

Deremeter	Sumbol	Conditions	Values			Unit
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit
Collector-base breakdown voltage	$BV_{CBO}$	Ι <sub>C</sub> = -50μΑ	-50	-	-	V
Collector-emitter breakdown voltage	$BV_{CEO}$	I <sub>C</sub> = -1mA	-50	-	-	V
Emitter-base breakdown voltage	$BV_{EBO}$	Ι <sub>Ε</sub> = -50μΑ	-5	-	-	V
Collector cut-off current	I <sub>CBO</sub>	V <sub>CB</sub> = -50V	-	-	-500	nA
Emitter cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> = -4V	-	-	-500	nA
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> = -5mA, I <sub>B</sub> = -0.25mA	-	-	-300	mV
DC current gain	h <sub>FE</sub>	V <sub>CE</sub> = -5V, I <sub>C</sub> = -1mA	100	250	600	-
Input resistance	R <sub>1</sub>	-	3.29	4.7	6.11	kΩ
Transition frequency	f <sub>T</sub> *4	V <sub>CE</sub> = -10V, I <sub>E</sub> = 5mA, f = 100MHz	-	250	-	MHz

\*1 Each terminal mounted on a reference land.

\*2 120mW per element must not be exceeded.

\*3 200mW per element must not be exceeded.

\*4 Characteristics of built-in transistor.

## •Electrical characteristic curves(T<sub>a</sub> = 25°C) <For DTR1(NPN)>

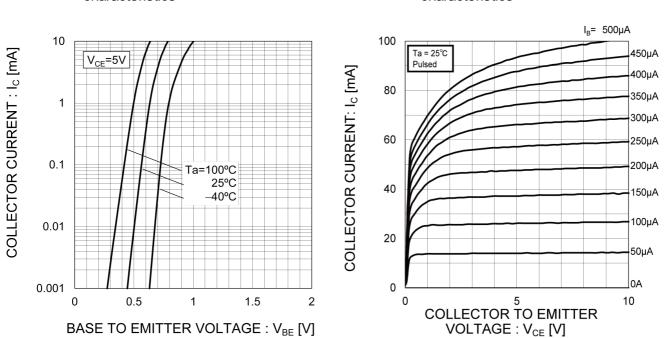
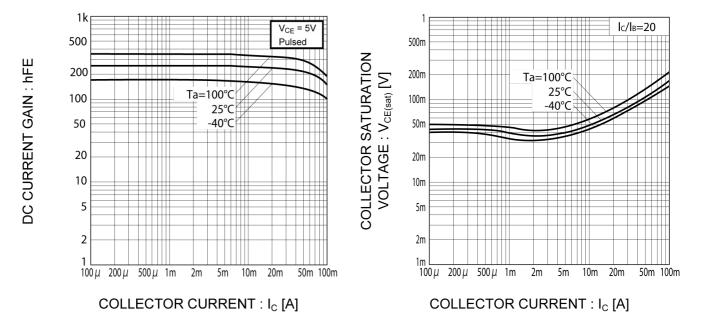


Fig.1 Grounded emitter propergation characteristics

Fig.3 DC current gain vs. collector current

Fig.4 Collector-emitter saturation voltage vs. collector current



# Fig.2 Grounded emitter output characteristics



## •Electrical characteristic curves(T<sub>a</sub> = 25°C) <For DTR2(PNP)>

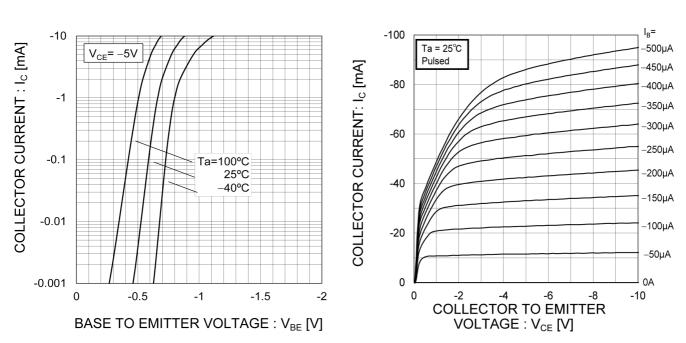
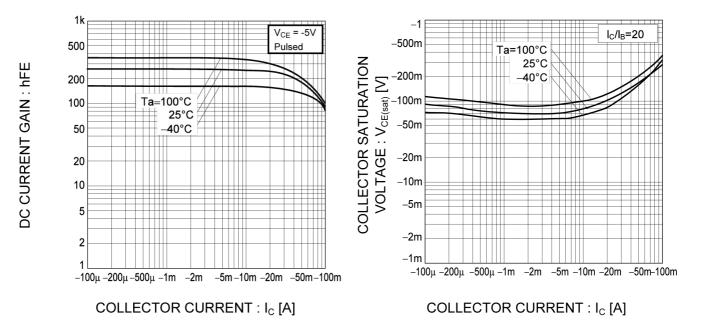


Fig.1 Grounded emitter propergation characteristics

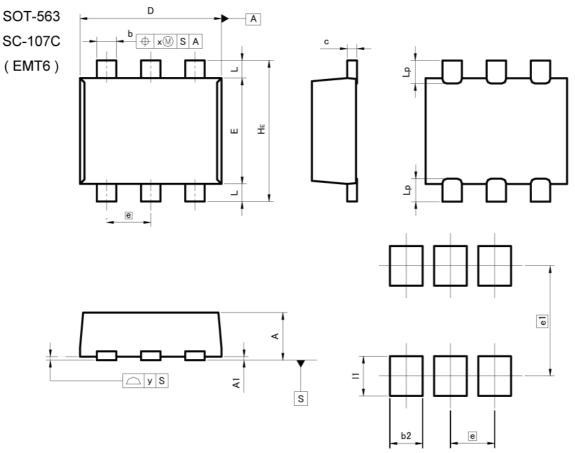
Fig.3 DC current gain vs. collector current

Fig.4 Collector-emitter saturation voltage vs. collector current





## Dimensions



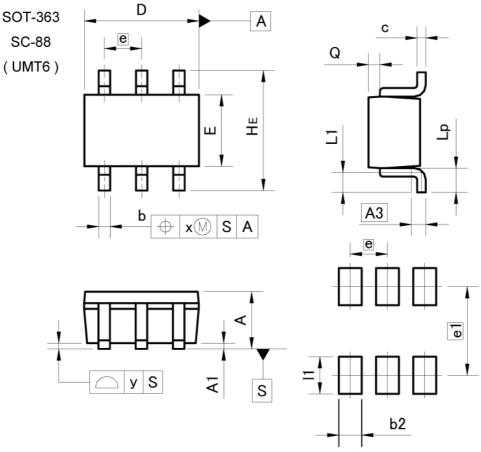
Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
A	0.45	0.55	0.018	0.022	
A1	0.00	0.10	0.000	0.004	
b	0.17	0.27	0.007	0.011	
с	0.08	0.18	0.003	0.007	
D	1.50	1.70	0.059	0.067	
E	1.10	1.30	0.043	0.051	
е	0.50		0.020		
HE	1.50	1.70	0.059	0.067	
L	0.10	0.30	0.004	0.012	
Lp	-	0.35	-	0.014	
x	-	0.10	-	0.004	
У	-	0.10	-	0.004	
DIM	MILIM	ETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
b2	-	0.37	-	0.015	
e1	1.25		0.049		
11	-	0.45	-	0.018	

Dimension in mm/inches



## Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

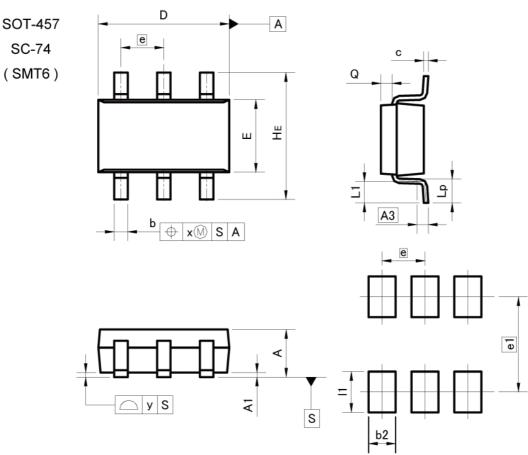
DIM	MILIMETERS		INC	HES		
DIM	MIN	MAX	MIN	MAX		
A	0.80	1.00	0.031	0.039		
A1	0.00	0.10	0.000	0.004		
A3	0.	25	0.0	10		
b	0.15	0.30	0.006	0.012		
с	0.10	0.20	0.004	0.008		
D	1.90	2.10	0.075	0.083		
E	1.15	1.35	0.045	0.053		
е	0.	0.65		0.026		
HE	2.00	2.20	0.079	0.087		
L1	0.20	0.50	0.008	0.020		
Lp	0.25	0.55	0.010	0.022		
Q	0.10	0.30	0.004	0.012		
х	-	0.10	-	0.004		
У	-	0.10	-	0.004		
DIM	MILIM	ETERS	INC	HES		
DIN	A ATA I	MAN	A 475.1	MAN		

DIM MILIME		ETERS	INC	HES
		MAX	MIN	MAX
b2	-	0.40	-	0.016
e1	1.55		0.0	61
1	-	0.65	-	0.026

Dimension in mm/inches



## Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
А	1.00	1.30	0.039	0.051
A1	0.00	0.10	0.000	0.004
A3	0.	25	0.0	10
b	0.25	0.40	0.010	0.016
с	0.09	0.25	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
е	0.	95	0.037	
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.20	0.30	0.008	0.012
х	-	0.20	-	0.008
У	-	0.10	-	0.004

DIM	MILIM	ETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
b2		0.60	-	0.024	
e1	2.10		0.0	83	
11	-	0.90	<del></del>	0.035	

Dimension in mm/inches



## Notice

### Precaution on using ROHM Products

1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment <sup>(Note 1)</sup>, transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

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CLASSⅣ		CLASSⅢ	

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  - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [C] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

### **Precautions Regarding Application Examples and External Circuits**

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

### **Precaution for Product Label**

QR code printed on ROHM Products label is for ROHM's internal use only.

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When disposing Products please dispose them properly using an authorized industry waste company.

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- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



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